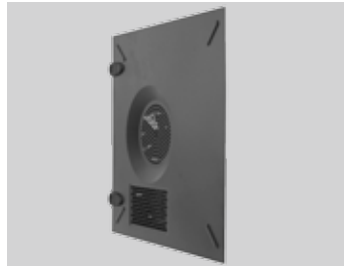
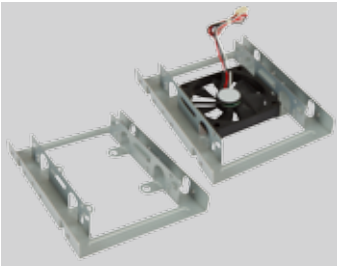


Z SERIES mATX CHASSIS



Features

TAC 2.0 Thermal Solution

Qualified for TAC 2.0, a mass ventilation hole side panel design strengthens thermal efficiency and cools down the entire system.

Cooling Fan

Optional 90mm auxiliary cooling fan at rear panel for better system cooling.

Tool-Free Installation and Easy Maintenance

Tool-free front panel, drive bays and I/O slots.

Side Panel Clips

The patented tool free installation side panel clips.

Stamped Motherboard Support

No MB standoffs installation required for faster MB installation.

Folded Edge

For safety installation. No sharp edges and debris.



Z SERIES

mATX CHASSIS



Z583 ■ ■



Z589 ■ □

Specifications

Case Size	Mini Tower Chassis
External Drive Bays	5.25" x 2, 3.5" x 2
Internal Drive Bays	3.5" x 1, 2.5" x 1
Front Ports	USB2.0 x 2, HD Audio
Dimensions (HxWxD)	363 x 180 x 370mm
w/o Front Panel	14.3" x 7.1" x 14.6"
MB Form Factor	Micro-ATX, Mini-ITX
I/O Expansion Slots	PCI-E Expansion Slot x 4
Power Supply	ATX 12V Form Factor, PSII Size
Thermal Solution	• Supports 80mm or 90mm Rear Fan • Intel Certified TAC 2.0
Safety	Meets RoHS, CE and FCC Class B Requirements
Security	Padlock Loop / Kensington Slot
Optional	• 80 or 90mm Rear Fan • eSATA • Chassis Intrusion Switch • USB 3.0 x 2 • 3.5" to 2.5" HDD/SSD Bracket

* The actual product is subject to change without prior notice. In Win Development Inc. reserves the right to make final modifications.